

Absolute Maximum Ratings		Values	Units
Symbol	Conditions <sup>1)</sup>		
$V_{DS}$		800	V
$V_{DGR}$	$R_{GE} = 20 \text{ k}\Omega$	800	V
$I_D$		36	A
$I_{DM}$		144	A
$V_{GS}$		$\pm 20$	V
$P_D$		700	W
$T_j, (T_{stg})$		-40 ... +150 (125)	°C
$V_{isol}$	AC, 1 min.	2 500	V
humidity	DIN 40 040	Class F	
climate	DIN IEC 68 T.1	40/125/56	
Inverse Diode			
$I_F = -I_D$		36	A
$I_{FM} = -I_{DM}$		144	A

Characteristics					
Symbol	Conditions <sup>1)</sup>	min.	typ.	max.	Units
$V_{(BR)DSS}$	$V_{GS} = 0, I_D = 0,25 \text{ mA}$	800	–	–	V
$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	2,1	3,0	4,0	V
$I_{DSS}$	$V_{GS} = 0$ } $T_j = 25 \text{ }^\circ\text{C}$	–	50	100	$\mu\text{A}$
		–	300	1000	$\mu\text{A}$
$I_{GSS}$	$V_{GS} = 20 \text{ V}, V_{DS} = 0$	–	10	100	nA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 23 \text{ A}$	–	170	210	m $\Omega$
$g_{fs}$	$V_{DS} = 10 \text{ V}, I_D = 23 \text{ A}$	16	33	–	S
$C_{CHC}$	$V_{GS} = 0$ $V_{DS} = 25 \text{ V}$ $f = 1 \text{ MHz}$	–	–	160	pF
$C_{iss}$		–	10	14	nF
$C_{oss}$		–	1,2	1,7	nF
$C_{rss}$		–	0,6	0,8	nF
$L_{DS}$		–	–	20	nH
$t_{d(on)}$	$V_{DD} = 400 \text{ V}$ $I_D = 23 \text{ A}$	–	60	–	ns
$t_r$		–	30	–	ns
$t_{d(off)}$	$V_{GS} = 10 \text{ V}$ $R_G = 4,7 \text{ }\Omega$ (SKM 181A3R: 3,3 $\Omega$ )	–	350	–	ns
$t_f$		–	70	–	ns
Inverse Diode <sup>8)</sup>					
$V_{SD}$	$I_F = 72 \text{ A}, V_{GS} = 0 \text{ V}$	–	0,9	1,2	V
$t_{rr}$	$T_j = 25 \text{ }^\circ\text{C} \text{ }^2)$	–	1200	–	ns
	$T_j = 150 \text{ }^\circ\text{C} \text{ }^2)$	–	–	–	ns
$Q_{rr}$	$T_j = 25 \text{ }^\circ\text{C} \text{ }^2)$	–	42	–	$\mu\text{C}$
	$T_j = 150 \text{ }^\circ\text{C} \text{ }^2)$	–	–	–	$\mu\text{C}$
Thermal characteristics					
$R_{thjc}$		–	–	0,18	°C/W
$R_{thch}$	$M_1$ , surface 10 $\mu\text{m}$	–	–	0,05	°C/W

Mechanical Data					
$M_1$	to heatsink, SI Units	4	–	5	Nm
	to heatsink, US Units	35	–	44	lb.in.
$M_2$	for terminals, SI Units	2,5	–	3,5	Nm
	for terminals, US Units	22	–	24	lb.in.
a		–	–	5x9,81	m/s <sup>2</sup>
w		–	–	130	g
Case	→ B 5 – 25			D15	

<sup>1)</sup>  $T_{case} = 25 \text{ }^\circ\text{C}$ , unless otherwise specified

<sup>2)</sup>  $I_F = -I_D, V_R = 100 \text{ V}, -di_f/dt = 100 \text{ A}/\mu\text{s}$

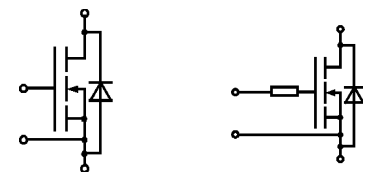
<sup>3)</sup> SKM 181 A 3 (with standard recovery body drain diode) can replace old SKM 181 F (with fast recovery body drain diode) only in DC-choppers and resonant inverters which do not use the fast recovery feature i. e.  $f_{sw} > f_{resonant}$ , but not for  $f_{sw} < f_r$  and not for PWM-inverters. In doubt please ask SEMIKRON.

## SEMITRANS® M Power MOSFET Modules

**SKM 181 A3 <sup>3)</sup>**  
**SKM 181 A3R \*)**



### SEMITRANS M1



**SKM 181 A3 SKM 181 A3R \*)**

### Features

- N Channel, enhancement mode
- Short internal connections avoid oscillations
- DCB-ceramic isolated copper baseplate
- All electrical connections on top for easy busbaring
- Large clearance (10 mm) and creepage distances (13 mm)
- UL recognized, file no. E63 532

### Typical Applications

- Switched mode power supplies
- DC servo and robot drives
- DC choppers
- Resonant and welding inverters
- AC motor drives
- Laser power supplies
- UPS equipment
- Plasma cutting
- Not suitable for linear amplification

\*) SKM 181 A3R has built-in gate resistor chips ("R")  $R_{ginternal} = 1,3\Omega$ , preferred typed for paralleling and for lower switching frequencies

**This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.**

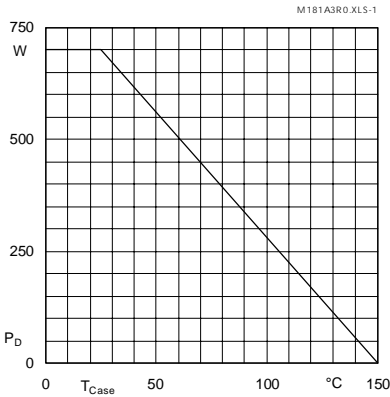


Fig. 1 Rated power dissipation vs. temperature

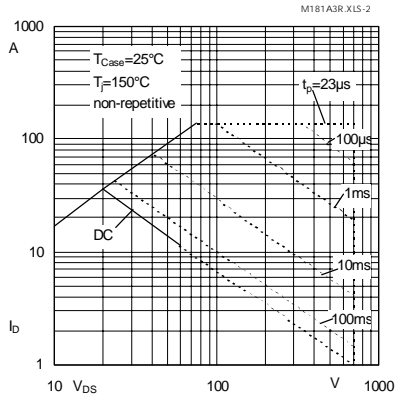


Fig. 2 Maximum safe operating area

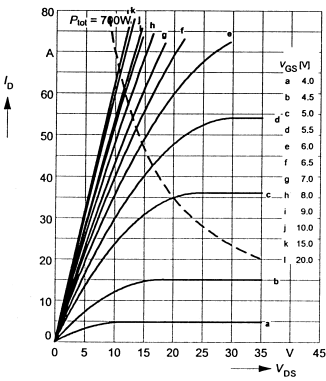


Fig. 3 Output characteristic

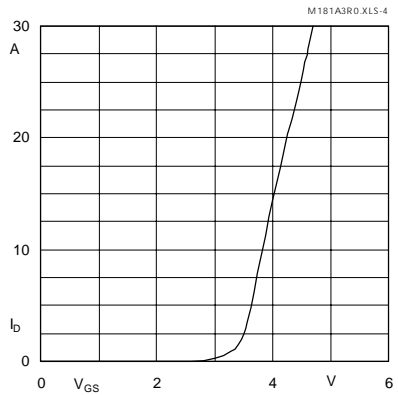


Fig. 4 Transfer characteristic

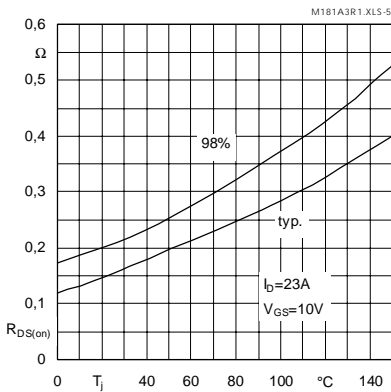


Fig. 5 On-resistance vs. temperature

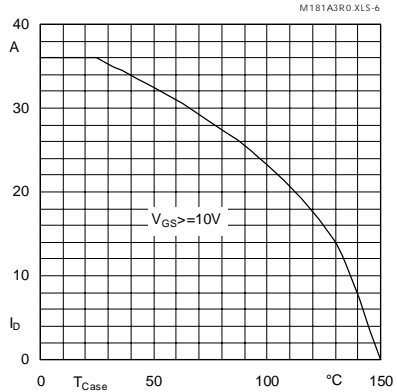


Fig. 6 Rated current vs. temperature

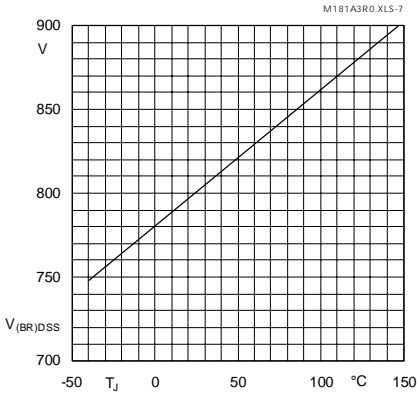


Fig. 7 Breakdown voltage vs. temperature

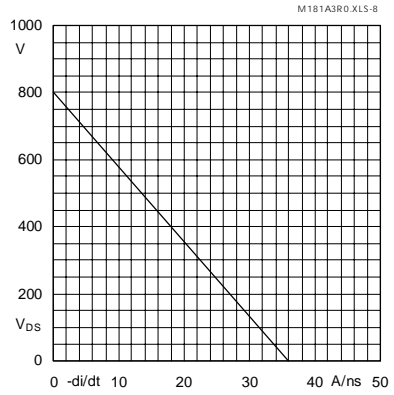


Fig. 8 Drain-source voltage derating

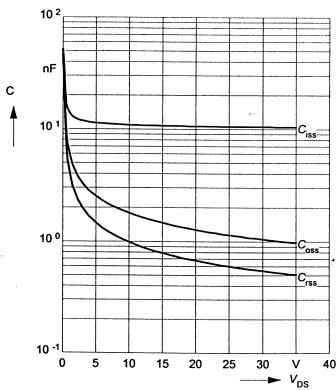


Fig. 9 Typ. capacitances vs. drain-source voltage

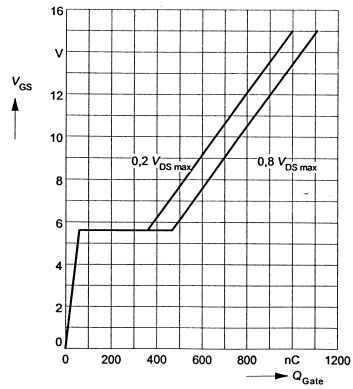


Fig. 10 Gate charge characteristic

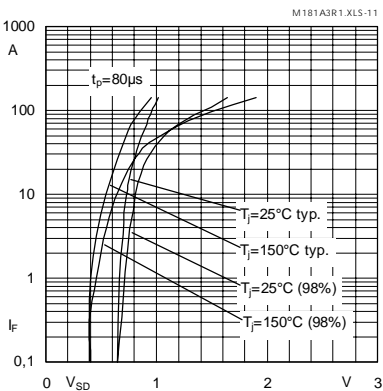


Fig. 11 Diode forward characteristic

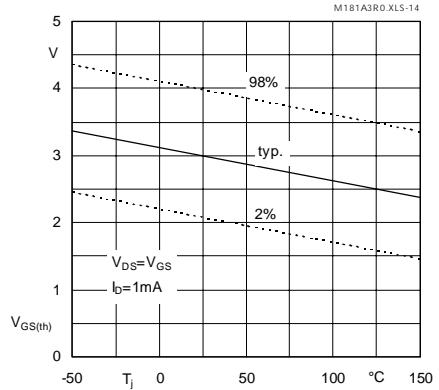


Fig. 14 Gate-source threshold voltage

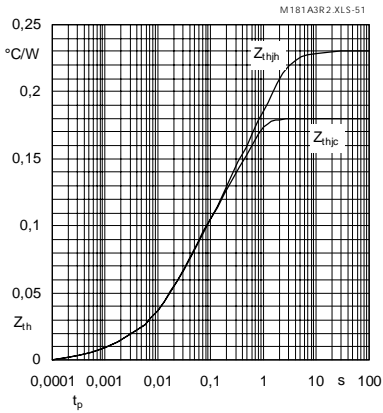


Fig. 51 Transient thermal impedance

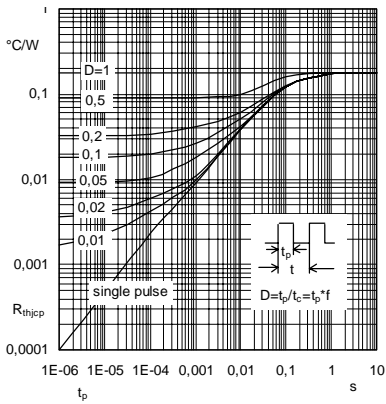


Fig. 52 Thermal impedance under pulse conditions

